

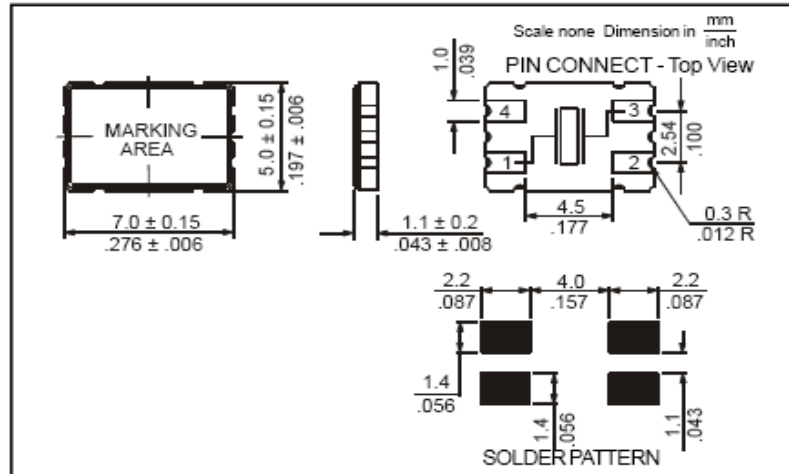
I 晶振电性能 Electrical Characteristics

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|-------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------|
| 1. 标称频率
Nominal Frequency | <u>14.7456</u> MHZ |
| 2. 振动模式
Mode of vibration | <u>基频 / AT 切</u> |
| 3. 工作温度范围
Operating Temperature Range | - <u>20</u> °C ~ + <u>70</u> °C |
| 4. 保存温度范围
Storage Temperature Range | -55°C ~ +125°C |
| 5. 频率偏差
Adjustment Tolerance | ± <u>20</u> ppm Max |
| 6. 温度偏差
Tolerance over the Temperature Range | ± <u>30</u> ppm Max |
| 7. 等效电阻
Equivalent Series Resistance | <u>50</u> Ω Max. at 25°C |
| 8. 静电容
Shunt Capacitance | <u>5.0</u> pF Max |
| 9. 气密性测试
Leakage | Gross Leak: $1.3 \times 10^{-5} \text{ Pa.m}^3/\text{s}$ Max
Fine Leak: $2.1 \times 10^{-9} \text{ Pa.m}^3/\text{s}$ Max |
| 10. 老化率
Aging | <u>±5ppm Max/Y</u> |
| 11. 外形尺寸
Dimensions | 7.0*5.0*1.1mm |

II. 测试条件 Test Condition

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|-----------------------------|----------------------------------------------------------------------|
| 1. 负载电容
Load Capacitance | <u>18.0</u> pF |
| 2. 激励功率
Level of Drive | <u>100</u> μ W |
| 3. 测试仪表 Equipment | HP-E5100 Net analysis meter/AX-150U
Heli0t-706/w Helium Leak Test |

SMD7050 晶体外型尺寸 Dimensions UNIT: mm

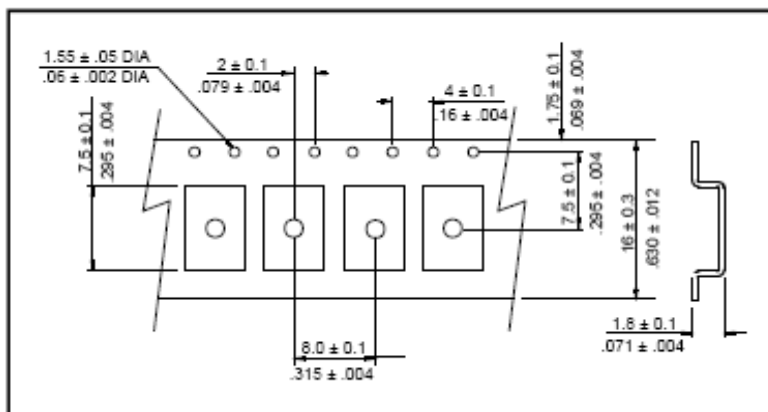
● OUTLINE DRAWING


SMD7050 晶体外型尺寸 (mm)

包装 PACKING

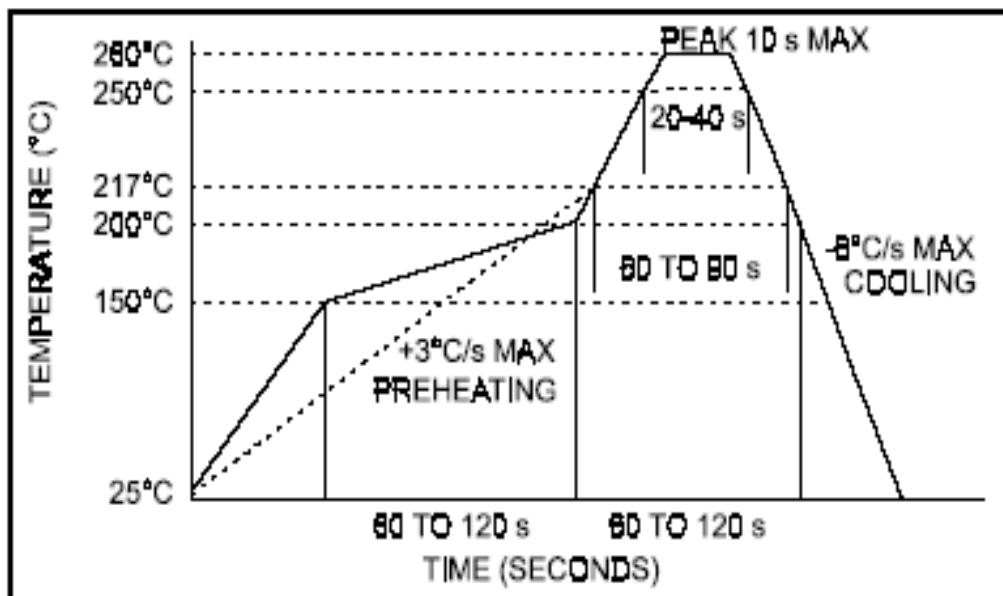
每 1000 只晶体进行编带包装，每 1 万只晶体放入一包装盒内。同时，包装形式也依赖于具体数量而更改。

Deposit 1000 pieces of the quartz crystal units in tape model, and pack enough bags in a packing case to make a 10,000 pieces package. The packing format may be subject to change by quantity.

SMD7050 编带尺寸图
● CARRIER TAPE DIMENSIONS


VIII. 可靠性试验项目 Reliability Test Items
1. 机械性能试验 Mechanical Performance Tests

试验项目 Test Item	试验方法 Test Method	规格 No. Spec. No
1-1 耐冲击 shock	从 75 厘米高, 3 次, 自由落在 3 厘米的硬木板上 Orient the sample in any attitude and drop it three times from a height of 75 cm onto a hardwood board with a thickness of 3 cm	A
1-2 耐振性 Vibration	振动频率 10~55Hz, 振幅 1.5mm 时间 1.5 分钟循环, 在 X、Y、Z 轴方向各 2 小时, 总计 6 小时。 Subject the sample to 1.5-minute cycles of frequencies of 10 to 55 Hz and amplitudes of 1.5mm for two hours in each of the X,Y, and Z directions, or 6 hours in total.	A
1-3 气密性 Leaking Test	用氦质谱仪测试或加压测绝缘电阻 Take measurements with a helium leakage detector, or measure insulation resistance under pressure.	E

1. 回流焊曲线图
● SOLDER REFLOW PROFILE


VIII. 可靠性试项目 Reliability Test Items

3. 环境测试 Environmental Tests

试验项目 Test Item	试验方法 Test Method	规格 No. Spec. No.
2-1 耐寒性 Cold	在-40℃环境中非工作状态放置 500 小时 Expose the sample in an inoperative mode to 500 hours in a -40℃	A
2-2 耐热性 Dry heat	在+85℃环境中非工作状态放置 500 小时 Expose the sample in an inoperative mode to 500 hours in a 85℃	B
2-3 耐湿性 Damp heat	在温度+65℃，湿度 95%环境中非工作状态放置 500 小时 Expose the sample in an inoperative mode to 500 hours in a 65℃, and 95%RH	B
2-4 热冲击 Thermal shock	在-40℃保持 30 分钟，100℃保持 30 分钟，循环 5 次。 Subject the sample to 5 temperature variation cycles at -40℃ for 30 minutes and +100℃ for the next 30 minutes in each cycles.	A

SPECIFICATIONS 规格

规格 No. Spec No.	规格 Specification
A	试验前后,频率变化在±5ppm 以内,等效电阻变化在要求范围内。 Any variation between the pre- and post-test frequencies shall remain within ±5ppm. The post-test equivalent series resistance shall remain within its specified tolerance range.
B	试验前后,频率变化在±10ppm 以内,等效电阻变化在要求范围内。 Any variation between the pre- and post-test frequencies shall remain within ±10ppm. The post-test equivalent series resistance shall remain within its specified tolerance range.
C	试验前后,外观未见明显损伤,气密性未破坏。 After each test, no visible damage shall be manifested, nor shall the hermetic seal break down.
D	上锡量至少在 90% 以上。 At least 90% of each dipped area shall be covered by fresh solder
E	$1 \times 10^{-2} \mu\text{Pa} \cdot \text{m}^3/\text{s}$ Max or $IR \geq 500\text{M}\Omega$

※测试在室温 $25 \pm 2^\circ\text{C}$ 环境中进行,每次试验后,样品必须在 $25 \pm 2^\circ\text{C}$ 环境中恢复 2 小时以上。

※ Measurements shall be taken at $25 \pm 2^\circ\text{C}$, and after each test, the sample be exposed to two hours at $25 \pm 2^\circ\text{C}$